What is claimed is:

1. A mounting structure for an electronic component, comprising:

a wiring circuit board having one face serving as a component mount surface and the other face serving as a solder-dip surface;

a wiring portion formed on at least one of the component mount surface and the solder-dip surface of the wiring circuit board;

a through-holed portion extending through the wiring circuit board and connected to be electrically conductive with the wiring portion;

a heat conducting apertured portion extending through the wiring circuit board and connected to be electrically conductive with the wiring portion, the heat conducting apertured portion being formed in the vicinity of the through-holed portion; and

a lead portion of the electronic component inserted to the through-holed portion from the component mount surface and soldered to the wiring circuit board.

2. The mounting structure according to claim 1, further comprising:

a heat collector portion extending from an end of the heat conducting apertured portion on the solder-drip surface, the heat collector portion being made of metal.

3. The mounting structure according to claim 2, wherein the heat collector portion is connected to be electrically conductive with an end of the through-holed portion on the solder-dip surface.

4. The mounting structure according to claim 1, wherein the heat conducting apertured portion is formed in a via hole.

5. The mounting structure according to claim 4, wherein the via hole is located at a center of the wiring portion in a widthwise direction thereof and the shortest distance between an inner wall of the via hole and an inner wall of the through-holed portion lies in a range equal to or greater than 0.5 mm and equal to or less than 3 mm.

6. The mounting structure according to claim 4, wherein two via holes are located in the wiring portion in a widthwise direction thereof and the shortest distance between a line segment interconnecting inner walls, at positions closest to the through-holed portion, of the via holes and an inner wall of the through-holed portion lies in a range equal to or greater than 0.5 mm and equal to or less than 3 mm.

7. The mounting structure according to claim 4, wherein two via holes are located in the wiring portion in a longitudinal direction thereof and the shortest distance between a center of a line segment interconnecting inner walls, at positions closest to the through-holed portion, of the via holes and an inner wall of the through-holed portion lies in a range equal to or greater than 0.5 mm and equal to or less than 3 mm.